

A collage of technology-related images: a city skyline at night with glowing network lines, a close-up of a circuit board with a central chip, and a network of glowing blue nodes and lines.

愛普科技股份有限公司 2026 年第一季法人說明會

2026/05/12

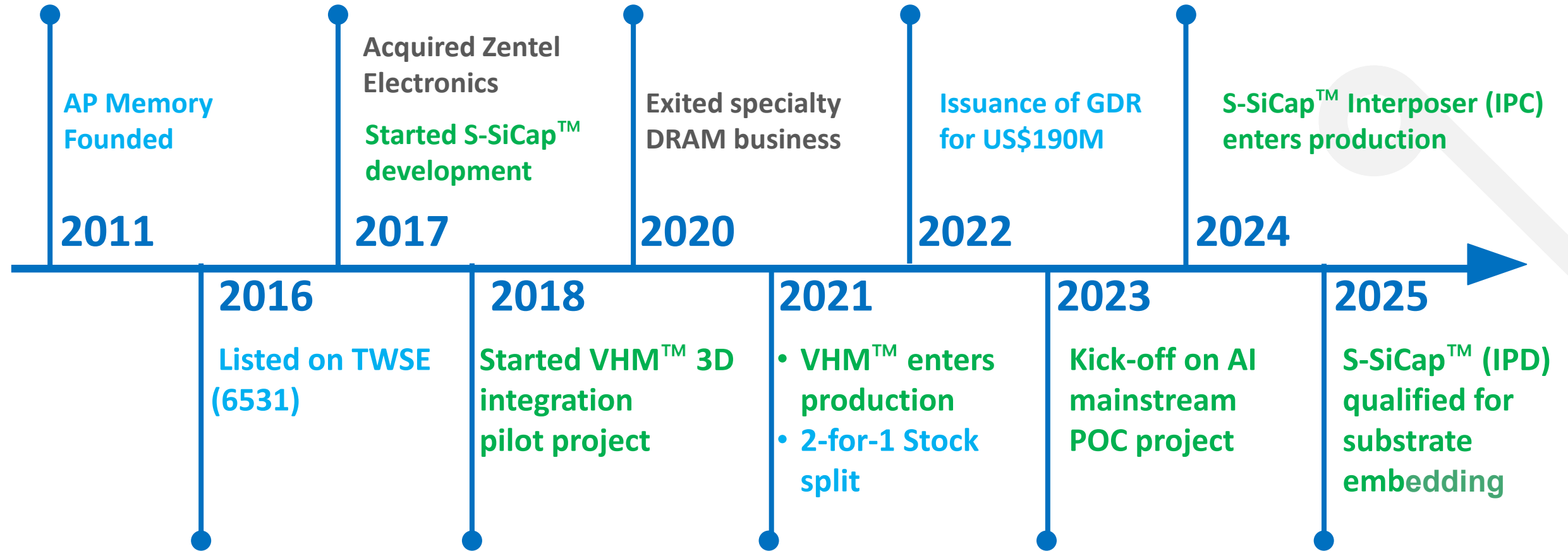
免責聲明

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公司基本資料

- 專注提供全球客戶客製化記憶體設計及解決方案之IC設計公司
- 總部位於台灣新竹台元科技園區
- 美/中/台三地合作研發；台灣營運
- 集團人數: ~277人
- 2016年於台灣證交所上市
- 已發行且流通在外股數: 1.62億股 (每股面額5元)

重要里程碑



Note:

VHM™ - Very High-bandwidth Memory; VHMStack™ - Very High-bandwidth Memory with multiple stacked layers

S-SiCap™ - Stack Silicon Capacitor, AP Memory's SiCap technology which uses a stack capacitor ; IPC - Capacitor in silicon Interposer ; IPD - Silicon capacitor embedded in substrate

Agenda



1 2026Q1 財務報告

2 營運狀況 及 未來展望

3 Q&A

01

2026Q1 財務報告

2026 Q1 合併損益表

(in NT\$K)	1Q26		4Q25		1Q25 ^{Note 1}		QoQ	YoY
營業收入(in US\$K)	66,261		59,978		29,681		10%	123%
平均匯率(US\$/NT\$)	31.69		31.15		32.85		2%	(4%)
營業收入	2,099,951	100%	1,868,104	100%	974,960	100%	12%	115%
營業毛利	969,865	46%	931,511	50%	453,138	46%	4%	114%
銷管費用	110,865	5%	85,977	4%	82,872	8%	29%	34%
研發費用	270,751	13%	273,233	15%	195,189	20%	(1%)	39%
營業費用	381,616	18%	359,210	19%	278,061	28%	6%	37%
營業利益	588,249	28%	572,301	31%	175,077	18%	3%	236%
外幣兌換利益	140,145	6%	251,140	13%	107,122	11%	(44%)	31%
其他業外收入	97,297	5%	85,242	5%	151,886	15%	14%	(36%)
營業外收入	237,442	11%	336,382	18%	259,008	26%	(29%)	(8%)
稅前淨利	825,691	39%	908,683	49%	434,085	44%	(9%)	90%
所得稅費用	165,725	8%	158,811	9%	88,760	9%	4%	87%
本期淨利	659,966	31%	749,872	40%	345,325	35%	(12%)	91%
淨利歸屬於：								
本公司業主	676,217	32%	765,577	41%	331,182	34%	(12%)	104%
非控制權益	(16,251)	(1%)	(15,705)	(1%)	14,143	1%	(3%)	(215%)
基本每股盈餘(NT\$)	4.15		4.71		2.04		(12%)	103%
加權平均股數(仟股)	162,798		162,687		162,443		0.07%	0.22%

Note 1 : 追溯調整因合併Onecent所產生之相關財務數據。

2026 Q1 擬制設算合併損益表:排除GDR未支用數之相關兌換影響

(in NT\$K)	1Q26		4Q25		1Q25 ^{Note 1}		QoQ	YoY
營業收入(in US\$K)	66,261		59,978		29,681		10%	123%
平均匯率(US\$/NT\$)	31.69		31.15		32.85		2%	(4%)
營業收入	2,099,951	100%	1,868,104	100%	974,960	100%	12%	115%
營業毛利	969,865	46%	931,511	50%	453,138	46%	4%	114%
銷管費用	110,865	5%	85,977	4%	82,872	8%	29%	34%
研發費用	270,751	13%	273,233	15%	195,189	20%	(1%)	39%
營業費用	381,616	18%	359,210	19%	278,061	28%	6%	37%
營業利益	588,249	28%	572,301	31%	175,077	18%	3%	236%
外幣兌換利益 ^{Note 2}	37,879	2%	72,853	4%	30,891	3%	(48%)	23%
其他業外收入	97,297	4%	85,242	5%	151,886	16%	14%	(36%)
營業外收入 ^{Note 2}	135,176	6%	158,095	9%	182,777	19%	(14%)	(26%)
稅前淨利 ^{Note 2}	723,425	34%	730,396	40%	357,854	37%	(1%)	102%
所得稅費用 ^{Note 2}	145,272	7%	123,154	7%	73,514	8%	18%	98%
本期淨利 ^{Note 2}	578,153	27%	607,242	33%	284,340	29%	(5%)	103%
淨利歸屬於：								
本公司業主 ^{Note 2}	594,404	28%	622,947	34%	270,197	28%	(5%)	120%
非控制權益	(16,251)	(1%)	(15,705)	(1%)	14,143	1%	(3%)	(215%)
基本每股盈餘(NT\$) ^{Note 2}	3.65		3.83		1.66		(5%)	120%
加權平均股數(仟股)	162,798		162,687		162,443		0.07%	0.22%

2026.03.31 Consolidated Balance Sheet

(in NT\$K)	2026.03.31		2025.12.31		2025.03.31 ^{Note 1}	
	AMT	%	AMT	%	AMT	%
資產總計	15,567,366	100%	14,740,272	100%	13,691,245	100%
現金及約當現金	8,765,915	56%	7,263,192	49%	5,126,877	37%
按攤銷後成本衡量之金融資產	2,843,170	18%	3,755,814	25%	4,784,838	35%
應收帳款	743,717	5%	588,490	4%	536,354	4%
存貨	1,190,175	8%	1,144,751	8%	1,113,669	8%
按公允價值衡量之金融資產	247,961	2%	243,583	2%	645,699	5%
採用權益法之投資	956,032	6%	962,914	6%	802,696	6%
其他資產	820,396	5%	781,528	6%	681,112	5%
負債總計	3,557,927	23%	2,376,226	16%	2,423,701	18%
短期借款	50,000	0%	200,000	1%	50,000	0%
合約負債	948,690	6%	939,560	6%	274,276	2%
應付帳款	528,496	4%	505,258	3%	230,184	2%
本期所得稅負債	494,261	3%	371,747	3%	355,374	3%
應付現金股利	1,139,702	7%	0	0%	1,137,180	8%
其他負債	396,778	3%	359,661	3%	376,687	3%
權益總計	12,009,439	77%	12,364,046	84%	11,267,544	82%
歸屬於本公司業主之權益	11,813,798	76%	12,242,597	83%	11,127,795	81%
非控制權益	195,641	1%	121,449	1%	139,749	1%
每股淨值 (NT\$)	72.55		75.24		68.48	

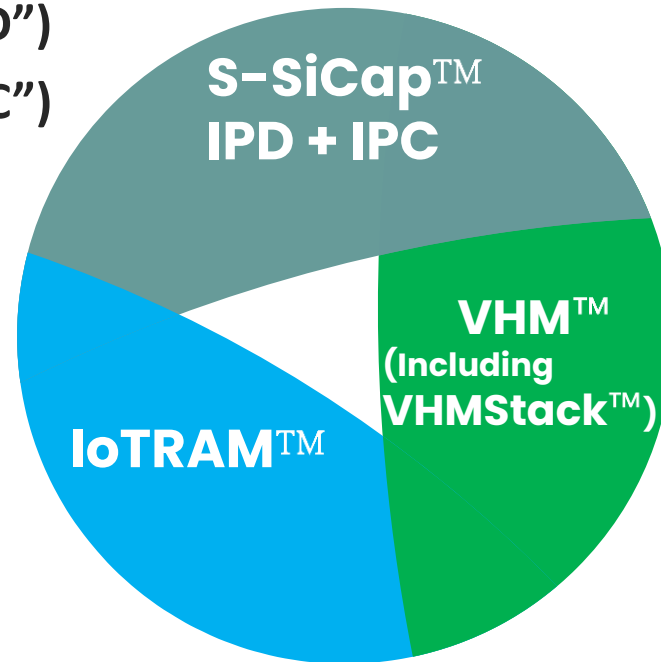
02

營運狀況 及 未來展望

$$\text{IoT} + \text{AI} = \text{IoTRAM}^{\text{TM}} + \text{S-SiCap}^{\text{TM}} + \text{VHM}^{\text{TM}}$$

Integrated **P**assive **D**eVICES (“IPD”)
Inter**P**osers with S-Si**C**apTM (“IPC”)

Best memory for IoT,
Second to none.



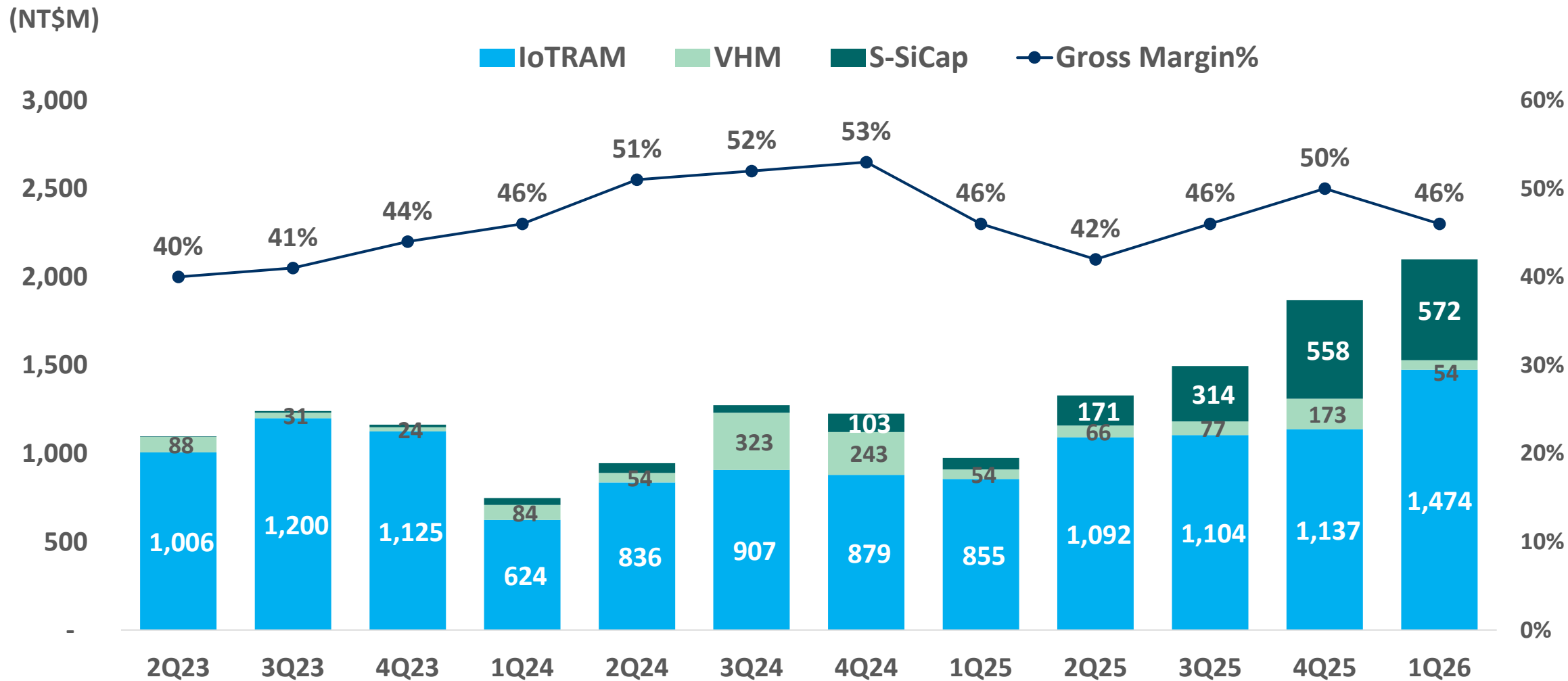
Best memory solutions
for AI/HPC

Note:

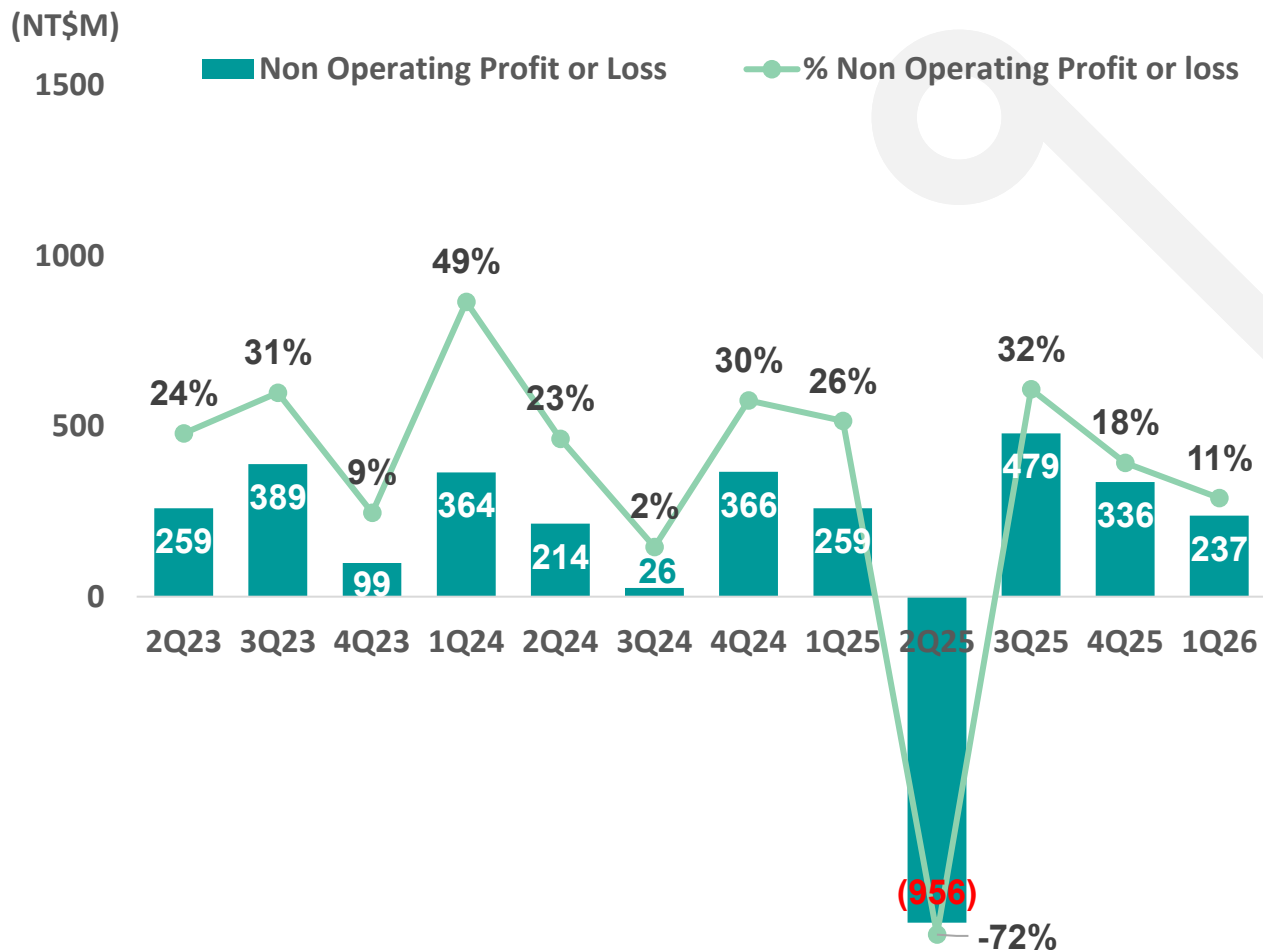
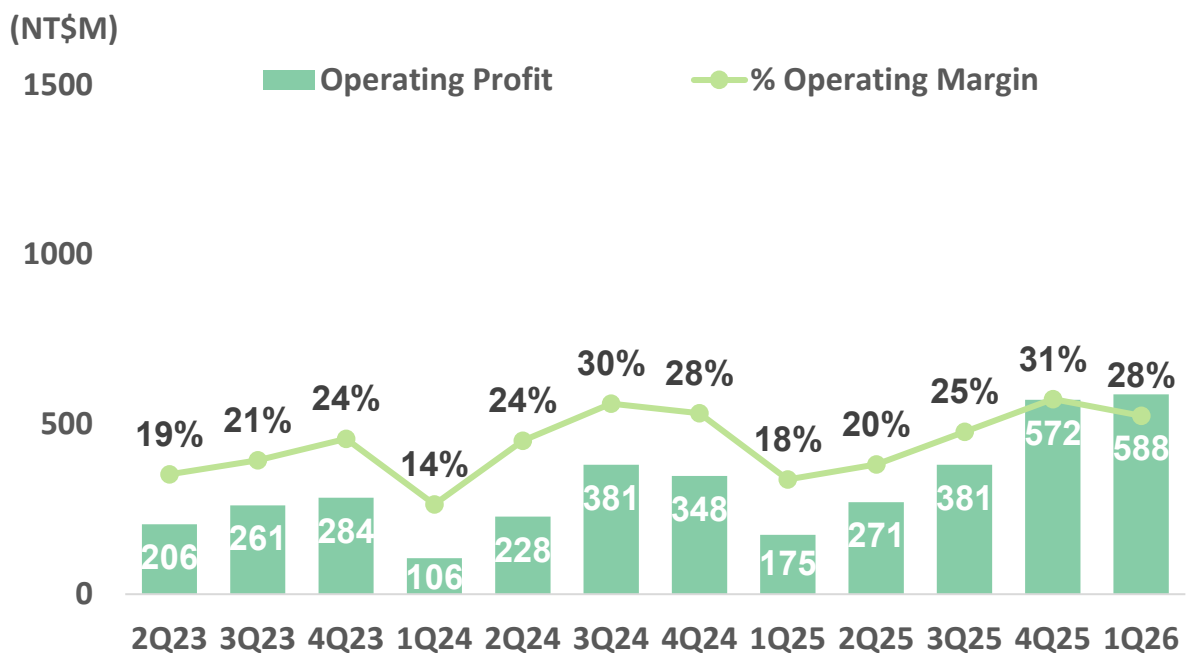
VHMTM - Very High-bandwidth Memory; **VHMStack**TM - Very High-bandwidth Memory with multiple stacked layers

S-SiCapTM - Stack Silicon Capacitor, AP Memory's SiCap technology which uses a stack capacitor ; **IPC** - Capacitor in silicon Interposer ; **IPD** - Silicon capacitor embedded in substrate

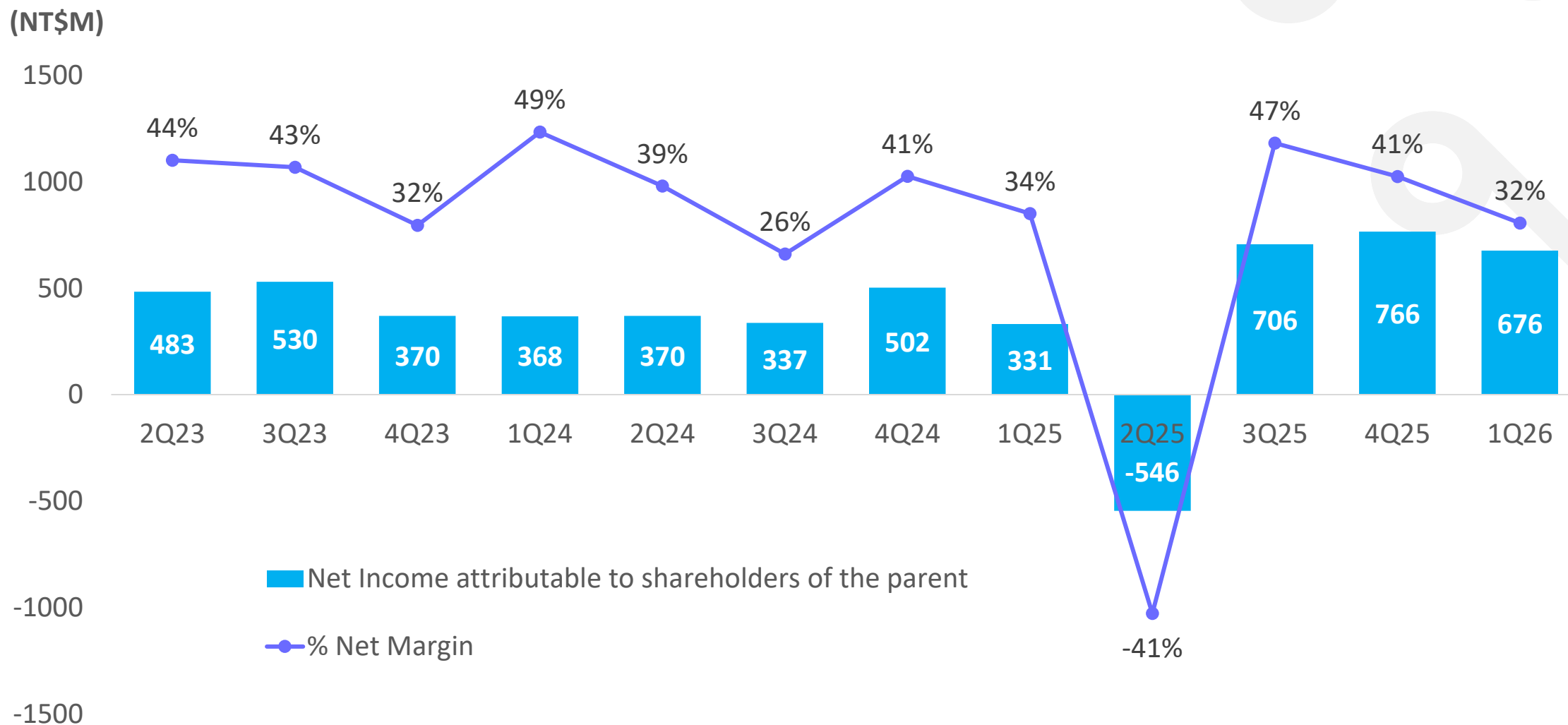
季度營收及毛利率趨勢



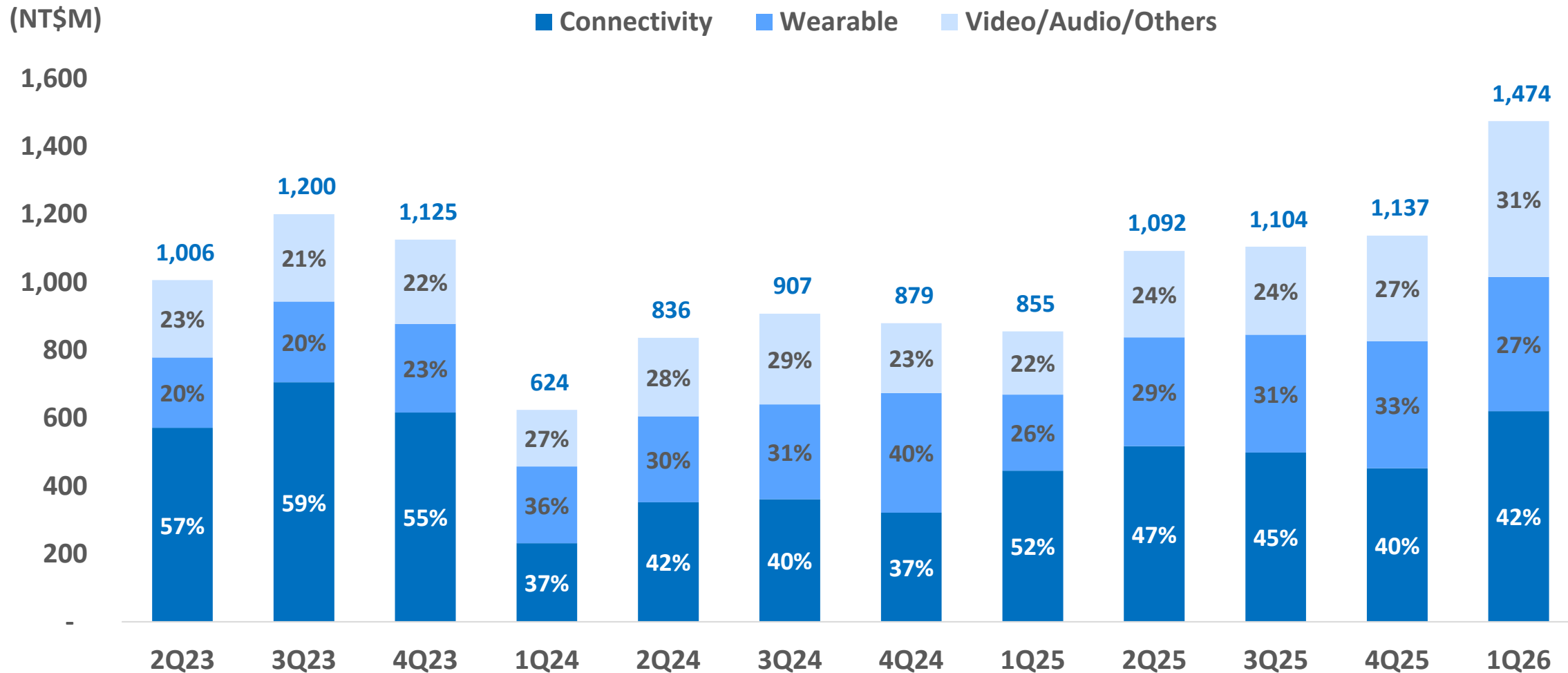
營業利益及業外收支



歸屬於母公司之稅後淨利



IoTRAM™ 季營收-應用別



- **Very Strong Market Demand**

- Growth came from all applications, especially display (ISP and home security camera) and connectivity (Cellular and Wi-Fi).
- New applications continue to emerge.

- **ApSRAM™ MP continues**

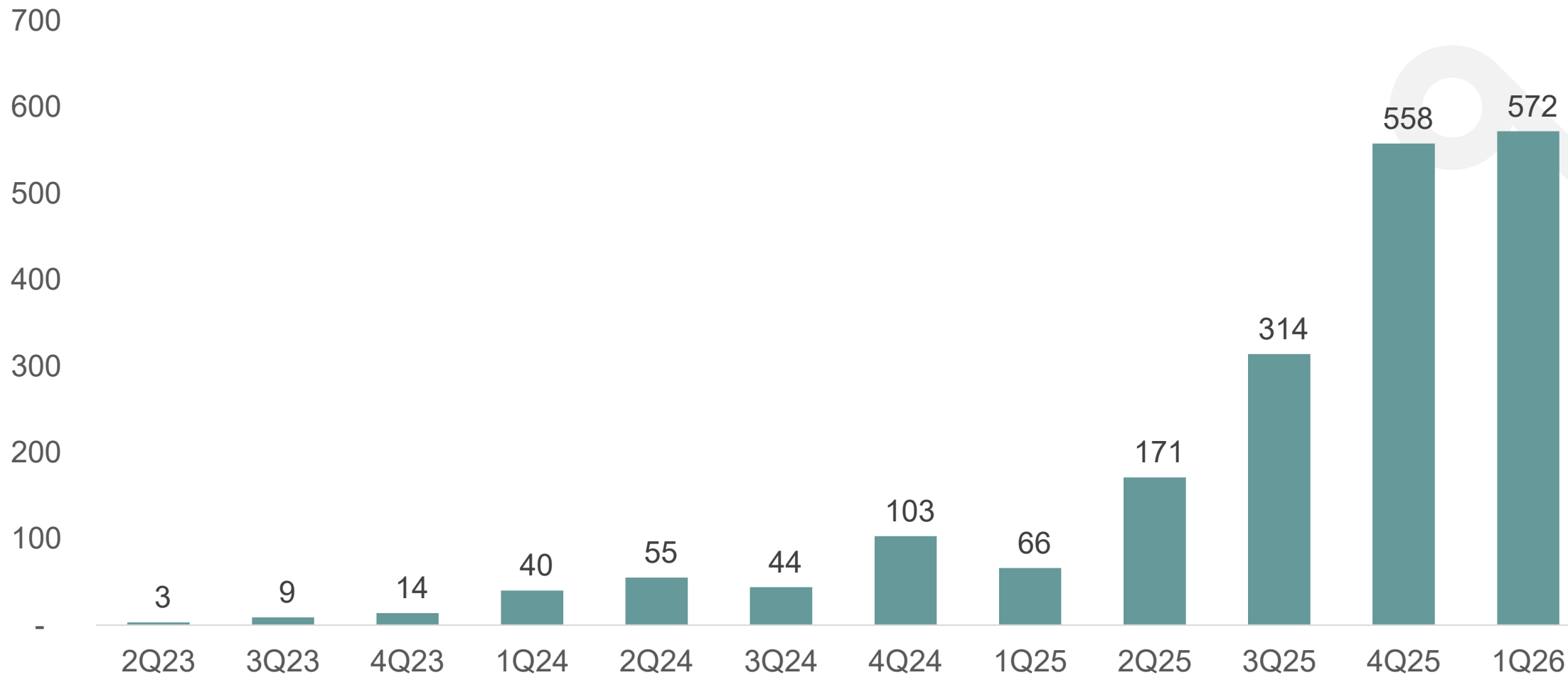
- More projects entering MP, 10+ design-in
- High density ApSRAM is starting design-in in Q2.

- **IoTRAM™ Market Position Stronger**

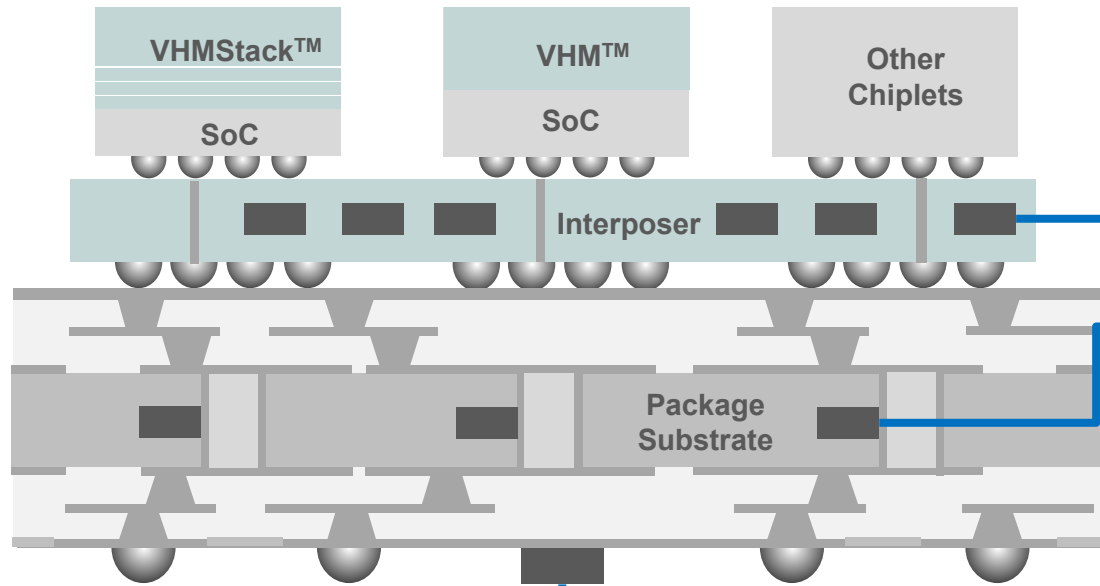
- The comprehensive and well-developed product lineup effectively meets the diverse needs of the market.
- Commodity long term shortage is driving customers towards IoTRAM™

S-SiCap™ 季營收

(NT\$M)



先進封裝領域之 IPC/IPD 產品佈局



1. IPC - Silicon Interposer ("-S") : ≤ 4 reticles

Capacitors embedded in silicon interposer
MP started in 2025, ramp continues

2. IPD in Substrate (IPD)—

Capacitors embedded in substrate
(For all varieties of 2.5D/3D HPC packages)
Qualified, MP in 2Q'26

3. Landside Capacitor (LSC/ IPD)—

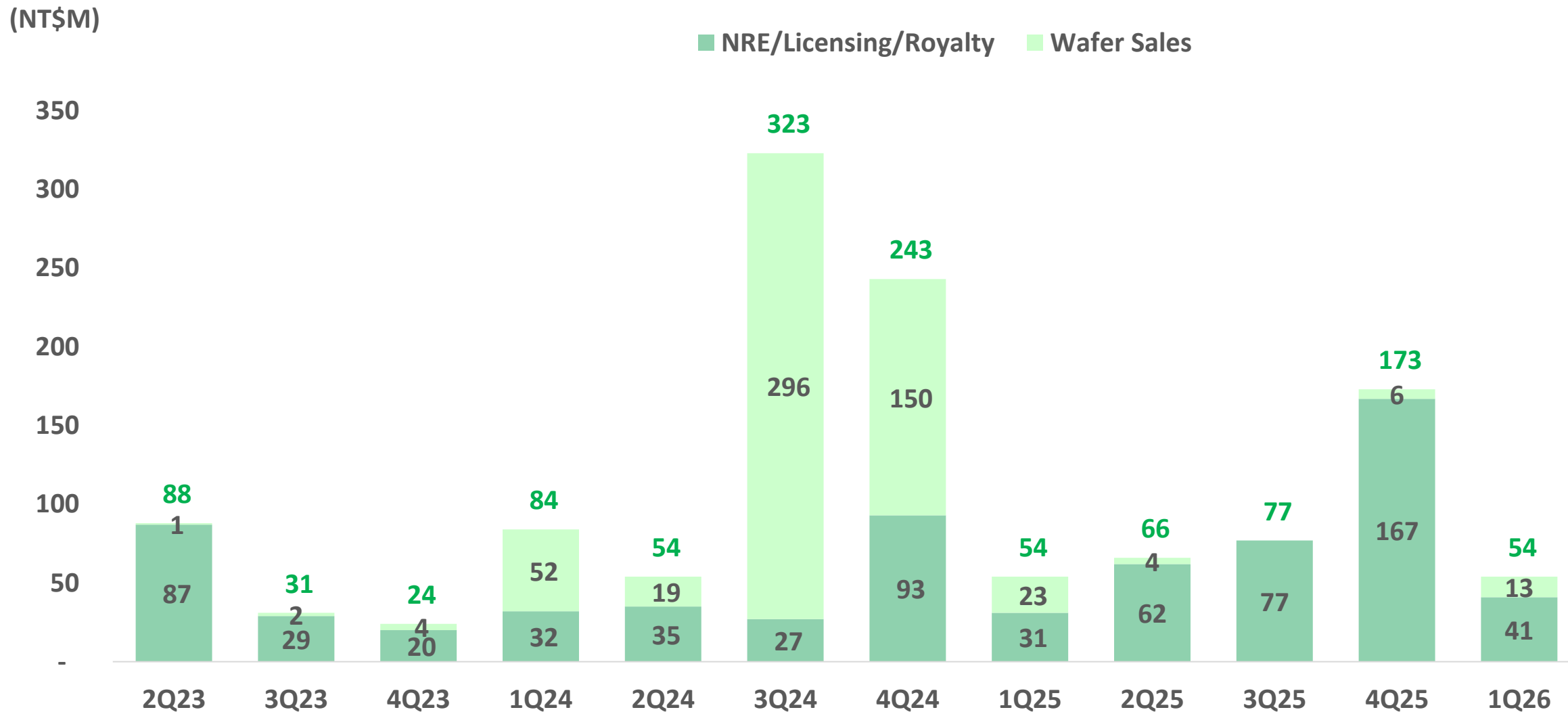
Capacitor placed on landside of package substrate
(Mainly mobile applications)
Qualified, MP in 2Q'26

Note:

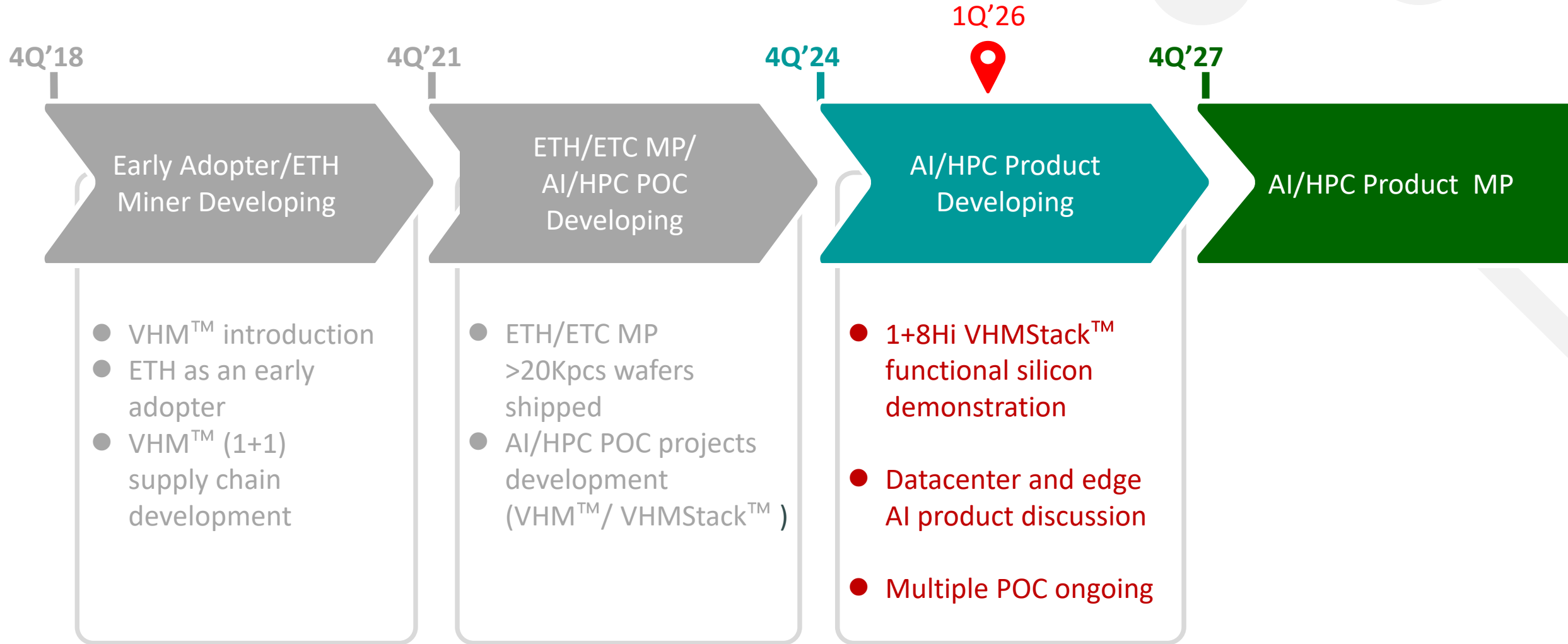
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VHM™ 季營收



VHM™ 與 VHMStack™ 導入時間軸



Note: Ethereum (ETH) and Ethereum Classic (ETC) are crypto currencies with Proof-of-Work consensus mechanism.

未來展望

- **IoTRAM™**
 - Very strong market demand, partly related to shortage in wider DRAM market
- **S-SiCap™**
 - **IPC:** Growth continues with minor tool relocation impact
 - **IPD:** MP starts in Q2'26. Strong demand driving rapid ramp-up in 2027
- **VHM™ / VHMStack™ Adoption Continues**
 - VHM™-enabled AI Accelerator product design ongoing

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Q&A

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